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## **Transistors**

#### Semiconductors

Impurities in the semiconductor material makes it a wonder material also called doping

*n*-type, donor - electrons as a majority carrier

*p*-type, acceptor - holes as a majority carrier

#### **Diodes**

Combination of two material *p*-type and *n*-type

Forward biased - like a conductor, majority carrier is the conductor, low resistance

Reverse biased - like a very high resistance, minority carrier is the conductor

Works as a one-way flow control

# Transistors

- It's a three layer (terminal) semiconductor device
- Two *n* and one *p* type or two *p* and one *n* type layers
- Two *n* and one *p* type is *npn transistor*
- Two *p* and one *n* type is *pnp transistor*
- Two types-
  - *Bipolar junction transistor(BJT)* Both electrons and holes participate in current flow
  - Unipolar junction transistor(UJT)
    Only one, either electrons or holes participate in current flow



# Transistors

- Three terminals Emitter, base, collector
- Middle layer or sandwich layer
  - thin compare to outer layers
  - lightly doped, less free carriers
- Can be considered as two diodes connected back to back







# Transistor operation

Forward biased diode - pn junction, emitter-base

Base- collector is open circuit.

Depletion layer is reduced and behave like a normal diode



Forward biased junction of a *pnp* transistor

# Transistor operation

Reverse biased diode - np junction, base collector

Depletion layer is increased and behave like a reverse biased diode



# Transistor operation

Forward biased emitter-base, and reverse biased base collector

Base is lightly doped, unable to handle large majority carriers. Diffuse to collector which is reverse bias, ready to accept the diffused holes.



# Modes of transistor operation

- Common base
- Common emitter
- Common collector

Particular terminal is common to both input and output

## **BJT** Transistors

The arrow on the emitter lead shows the direction of current flow, when emitter-base junction is forward biased, it is always from p to n

Currents are positive when flows inside the transistors

For a *pnp* transistor it will be inward and for *npn* transistor it will be outward





pnp transistor

npn transistor

Current direction changes in the above two configuration

Base is common to input and output

Emitter-base junction is forward biased

Collector-base junction is reverse biased

Biasing remains same irrespective of *npn* or *pnp* 



Input characteristics for a common base silicon transistor

- -like a pn junction
- V<sub>CB</sub> not having major influence



Active region - base-emitter forward biased and collectorbase is reverse biased



$$I_E = I_B + I_C$$

Current in base is negligible. Current in emitter and collector is almost same.

Current gain less than unity

 $\alpha = I_C / I_E ~(0.90 \text{ - } 0.998)$ 



## Common - emitter

Emitter is common to input and output

Base-emitter junction is forward biased

Collector-emitter junction is reverse biased

Biasing remains same irrespective of *npn* or *pnp* 



## Common - emitter

- Base-emitter *pn* junction, forward biased
- Base current is in micro ampere
- $V_{CE}$  does not have major influence on  $I_{B}$



## Common - emitter

- Base-emitter *pn* junction, forward biased & base collector is reverse biased.
- Base current is in micro ampere, collector current in milli ampere
- High current gain
- Cutoff region below  $I_B = 0$



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## Common - emitter

$$I_C = \alpha \ I_E + I_{CBO}$$

I<sub>CBO</sub> current collector to base when emitter is open, minority current

 $I_{E} = I_{B} + I_{C}$  $I_{C} = \alpha (I_{B} + I_{C}) + I_{CBO}$ 

$$I_{\rm C} = \frac{\alpha I_{\rm B}}{1 - \alpha} + \frac{I_{\rm CBO}}{1 - \alpha}$$

VBB VRR 

$$\beta = \frac{\alpha}{1 - \alpha} \qquad \alpha = \frac{\beta}{1 + \beta}$$

Current Gain  $\beta = I_C/I_B$  $\beta = (50 - 250)$ 

## Common - collector

Collector is common to input and output

Base-collector junction is forward biased

Base-emitter junction is reverse biased

Biasing remains same irrespective of *npn* or *pnp* 

Characteristics same as common emitter

Input resistance is very high and output resistance is low.



## DC Biasing - BJT

Biasing - shifting the mean operating point. To avoid operation in

- Non-linear region
- Saturation region
- Cut-off region
- Max. power consumption
- Linear region operation Base-emitter forward bias Base-collector reverse bias
- Cutoff region Base-emitter reverse bias
- Saturation region Base-emitter forward bias Base-collector forward bias



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## DC Biasing - BJT



Clipping due to saturation region, base-collector junction gets forward biased

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## DC Biasing - BJT



Clipping due to cutoff region.

## DC Biasing - BJT



Chosen Quiescent point is good for the given input signal

## **Fixed Bias Circuit**

Biasing is decided by the resistance  $R_B$  and  $R_C$  connected to base and collector. These decide the mean operating point. For DC analysis, circuit without capacitor can be analysed.





## **Fixed Bias Circuit**



Figure 4.4 Base–emitter loop.

## **Fixed Bias Circuit**





Figure 4.5 Collector-emitter loop.

## BJT







# Common baseCommon emitterCommon collectorCommon emitter has a good voltage gainCommon base, good voltage gain, disadvantage of low input

Common base, good voltage gain, disadvantage of low input impedance

Common collector, voltage gain ~ 1, high input impedance and low output impedance. Good for impedance matching

#### **Unipolar Junction Transistors**

Unipolar device solely depends on electron (*n*-channel) or hole (*p*-channel) conduction. Three terminal device.

Field Effect Transistor (FET) is a Unipolar device

Conduction is controlled by the electric field. No need of direct contact between the controlling and controlled quantities

JFET - Junction Field Effect Transistor

MOSFET - Metal Oxide Semiconductor FET

Major part is *n*-type material channel, embedded between two *p*-type material.

Two ends of the *n*- type material channel are Drain (D) and source (S)

Two *p*-type material are connected together and referred as Gate (G)

Two *pn* junctions, depletion region at each junction



 $V_{GS} = 0$  v and  $V_{DS}$  some positive value

Gate and Source are same potential

Electrons will flow from source to drain as in *n* type semiconductor

 $I_D = I_S$ 

Resistance of *n*-channel acts between drain and source

Depletion region is wider near the top of *p*-region



Resistance of *n*-channel is uniform along the length. This works as a potential divider.

This leads to a variable reverse bias along the length. Maximum at top of *p*-material Reverse bias will depend on the current in *n*-channel. More the current more the potential drop



- Initially it follows Ohm's law (almost straight line)
- Later depletion layer widens
- Pinch off level depletion layer cannot increase more (very high resistance)
- Give a feeling  $I_D$  will be zero. This is not possible





 $V_{GS} < 0$  v and  $V_{DS}$  some positive value

Gate to source voltage non zero

 $V_{GS} < 0$  v more reverse bias and hence reduces saturation level for  $I_D$ . This will further reduce with reduction in  $V_{GS}$ 



Level of  $V_{GS}$  when  $I_D = 0$  is defined as  $V_P$ 

 $V_P$  is negative for *n*-channel and positive for *p*- channel

Region left of locus of pinch off values is called as ohmic or voltage controlled resistance ( $V_{DS}$ ). Possible use in automatic gain control, where resistance can be controlled by voltage.



*p*-channel type

Behaves exactly same as *n*-channel type. Current direction and the polarities for  $V_{GS}$  and  $V_{DS}$ changes.  $V_{GS}$  is positive and this will create more reverse bias.



*p*-channel type, characteristics

 $V_{P} > 0$ 

Current is unbounded in the breakdown region. This will damage the transistor.



#### Metal Oxide Semiconductor Field Effect Transistors - MOSFET

*n*-type channel is constructed over a *p*-type substrate in form of slab

Many times substrate and source are connected internally and it is a three terminal device

Source and drain are connected at each end of *n*-channel

Gate and *n*-channel are separated by insulator  $SiO_2$  layer (dielectric)



#### **Depletion type MOSFET-Basic operation**

$$V_{GS} = 0v, V_{DS} > 0$$

Operation similar to JFET

Current flows through *n*channel. Free electrons are attracted to positive terminal of drain. Channel ohmic resistance is offered.



oon oon ahaan ahaa kana kaadaan indoning ahaan ahaa ahaa Minimuu ahaa in shiri sooraa kaakaan ahaa ahaa ahaa ahaa

## **Depletion type MOSFET-Basic operation**

When  $V_{GS}$  is negative, the electric field will pressure electrons towards *p*-type substrate, hence reduce free carrier in *n*-channel or depleting the majority carrier

When  $V_{GS}$  is positive it enhances the current. It is limited by the maximum current capacity of the device



by negative potential at gate

*p*-type substrate in form of slab with no *n*-channel

Many times substrate and source are connected internally and it is a three terminal device

Source and drain are connected to two *n*-doped region

Gate and *p*-substrate are separated by insulator  $SiO_2$  layer (dielectric)



When  $V_{GS} = 0$  and  $V_{DS} > 0$ 

No link between two *n*-doped region and hence no current

 $V_{GS}$  and  $V_{DS} > 0$  This will push the holes away from the SiO<sub>2</sub> edge and attracts electrons from the *p*-substrate. When sufficient voltage is applied it creates a *n*channel, this is called threshold voltage V<sub>T</sub>



- If  $V_{GS}$  is increased beyond threshold voltage,  $I_D$  will increase.
- If  $V_{GS}$  is kept constant beyond threshold voltage, and  $V_{DS}$  is increased then  $I_D$  will reach saturation level similar to JFET (pinch off)



Values less than threshold value  $I_D$  is zero

 $V_{GS}$  increases  $V_{DSsat}$ 



Drain characteristics of an *n*-channel enhancement-type MOSFET with  $V_T = 2$  V and  $k = 0.278 \times 10^{-3}$  A/V<sup>2</sup>.

#### **Darlington Pair circuit**

Used as high current current component. Current amplification of the order of  $\beta^2$  Can be easily integrated with microcontroller for interfacing DC motor, relays etc.



#### **MOSFET** as relay driver

When photodiode not conducting Gate is positive and no current in MOSFET. When photodiode is conducting Gate is grounded and current is passed through MOSFET.



## **BJT and UJT**

- BJT Current controlled devices
  - electron & holes participate in conduction
  - Robust in handling
- UJT Voltage controlled devices
  - Only one type of carrier participate in conduction
  - Smaller in size and more devices can be packed
  - Sensitive to static charge (MOSFET)
  - Very high input impedance
  - Less noisy

#### **BJT symbols**







## **UJT symbols**



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